

**Assembly Transfer of Small Body Punched LFCSP Products to Amkor Philippines  
AP1**

**Qualification Plan Summary of 4x4mm and 5x5mm  
Punched LFCSP at Amkor Philippines**

<b>QUALIFICATION PLAN</b>			
<b>TEST</b>	<b>SPECIFICATION</b>	<b>SAMPLE SIZE</b>	<b>EXPECTED COMPLETION DATE</b>
Temperature Cycle (TC)*	<i>JEDEC JESD22-A104</i>	3 x 77	August 2015
Unbiased Highly Accelerated Stress Test (uHAST)*	<i>JEDEC JESD22-A118</i>	3 x 77	August 2015
Solder Heat Resistance (SHR)*	<i>JEDEC/IPC J-STD-020</i>	3 x 11	August 2015
High Temperature Storage (HTS)	<i>JEDEC JESD22-A103</i>	1 x 77	August 2015
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	<i>JEDEC JESD22-C101</i>	3/voltage	August 2015

\*Preconditioned per JEDEC/IPC J-STD-020